

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Ming-Hsi YEH</td><td>07/07/2011</td></tr><tr><td>Hsien-Hsin LIN</td><td>07/14/2011</td></tr><tr><td>Ying-Hsueh CHANG CHIEN</td><td>07/18/2011</td></tr><tr><td>Yi-Fang PAI</td><td>07/14/2011</td></tr><tr><td>Chi-Ming YANG</td><td>07/07/2011</td></tr><tr><td>Chin-Hsiang LIN</td><td>07/18/2011</td></tr></tbody></table>	Name	Execution Date	Ming-Hsi YEH	07/07/2011	Hsien-Hsin LIN	07/14/2011	Ying-Hsueh CHANG CHIEN	07/18/2011	Yi-Fang PAI	07/14/2011	Chi-Ming YANG	07/07/2011	Chin-Hsiang LIN	07/18/2011	
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RECEIVING PARTY DATA															
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.														
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park														
City:	Hsinchu														
State/Country:	TAIWAN														
Postal Code:	300														
PROPERTY NUMBERS Total: 1															
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>13189108</td></tr></tbody></table>	Property Type	Number	Application Number:	13189108											
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Application Number:	13189108														
CORRESPONDENCE DATA															
Fax Number: (703)518-5499 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>															
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ATTORNEY DOCKET NUMBER:	T5057-B505														
NAME OF SUBMITTER:	Randy A. Noranbrock														
Total Attachments: 2 source=efiledassgn#page1.tif source=efiledassgn#page2.tif															

OP \$40.00 13189108

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PATENT
REEL: 026636 FRAME: 0242

Docket No. T5057-B505

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- | | |
|---------------------------|--------------------|
| 1) Ming-Hsi YEH | 4) Yi-Fang PAI |
| 2) Hsien-Hsin LIN | 5) Chi-Ming YANG |
| 3) Ying-Hsueh Chang CHIEN | 6) Chin-Hsiang LIN |

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at **No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.**

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

METHOD OF FABRICATING AN INTEGRATED CIRCUIT DEVICE

(a) for which an application for United States Letters Patent was filed on 7-22-2011, and identified by United States Patent Application No. 13/189,108; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Ming-Hsi Yeh
Name: Ming-Hsi YEH

7/7 '11
Date:

2) Hsien Hsin Lin
Name: Hsien-Hsin LIN

7/14, 2011
Date:

3) Ying-Hsueh Chang Chien
Name: Ying-Hsueh Chang CHIEN

7/18, 2011
Date:

4) Yi-Fang PAI
Name: Yi-Fang PAI

7/14. 2011
Date:

5) Chi-Ming Yang
Name: Chi-Ming YANG

7/7. 2011
Date:

6) Chin-Hsiang LIN
Name: Chin-Hsiang LIN

7/18. 2011
Date: